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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/511,396	03/23/2005	Masahiro Hatakeyama	042879	2154
38834	7590	09/26/2007	EXAMINER	
WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP			WELLS, NIKITA	
1250 CONNECTICUT AVENUE, NW			ART UNIT	PAPER NUMBER
SUITE 700			2881	
WASHINGTON, DC 20036				
MAIL DATE		DELIVERY MODE		
09/26/2007		PAPER		

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)
	10/511,396	HATAKEYAMA ET AL.
	Examiner Nikita Wells	Art Unit 2881

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) Responsive to communication(s) filed on 25 July 2007.
 2a) This action is **FINAL**. 2b) This action is non-final.
 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) Claim(s) 1-17 is/are pending in the application.
 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
 5) Claim(s) _____ is/are allowed.
 6) Claim(s) 1-17 is/are rejected.
 7) Claim(s) _____ is/are objected to.
 8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) The specification is objected to by the Examiner.
 10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) All b) Some * c) None of:
 1. Certified copies of the priority documents have been received.
 2. Certified copies of the priority documents have been received in Application No. _____.
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) Notice of References Cited (PTO-892)
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
 3) Information Disclosure Statement(s) (PTO/SB/08)
 Paper No(s)/Mail Date 02/11/05, 10/15/04.
- 4) Interview Summary (PTO-413)
 Paper No(s)/Mail Date. _____.
 5) Notice of Informal Patent Application
 6) Other: _____.

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

2. Claims 1-17 are rejected under 35 U.S.C. 102(e) as being anticipated by Chondroudis et al. (2004/0071888 A1).

With respect to claim 1, 5, 6, 8, and 14, Chondroudis et al. disclose (Abstract; Fig. 1; and paragraphs [0005, 0041, 0073, 0074, 0075, 0083, 0084, 0123, 0128, and 0139]) a method and apparatus of forming a resistive film on a surface of a sample comprising the steps of: rotating the sample at a rotational speed with the sample being held in a substantial horizontal situation; dropping a liquid film material on the sample surface while the sample is being rotated, to form a resistive film thereon; and dropping a solvent which solves the resistive film formed on the sample surface while the sample is being rotated at a rotational speed, thereby dissolving a part of the resistive film to obtain the resistive film having a desired level of thickness.

With respect to claims 4, 7, 12, and 16, Chondroudis et al. disclose (paragraph [0139]) a method or system wherein the sample is at least one of a semiconductor wafer, photo mask and reticle mask.

With respect to claims 2 and 9, Chondroudis et al. disclose (paragraph [0075]) a method wherein the desired level of the thickness of the resistive film is 0.1 nm to 10 nm.

With respect to claims 13, 15, and 17, Chondroudis et al. disclose (paragraphs [0123, 0128, and 0141]) a method of manufacturing a semiconductor device comprising the step of: inspecting a semiconductor wafer in the middle of a manufacturing process and/or after completion of the manufacturing process by a surface inspection method.

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 3, 10, and 11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chondroudis et al. (2004/0071888 A1).

With respect to claims 3, 10, and 11, Chondroudis et al. disclose (as mentioned above in paragraph #2) a method and apparatus of forming a resistive film on a surface of a sample while dropping a liquid film material on the sample surface while the sample is being rotated.

Chondroudis et al. fail to specifically disclose the use of a method wherein the resistive film is water-soluble. However, Chondroudis et al. does disclose (paragraph [0074]) various ways of dissolving or dispersing the material in order to facilitate the formation of a thinner film on the substrate. It would be only a matter of obvious design choice to use water as the dissolving medium in the facilitation of the formation of a thinner film on the substrate.

Conclusion

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nikita Wells whose telephone number is (571) 272-2484. The

examiner can normally be reached on 8:30 AM - 5:00 PM. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Robert Kim can be reached on (571) 272-2293. The central fax phone number for the organization where this application or proceeding is assigned is (571) 273-8300.

6. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Nikita Wells, Primary Examiner,

Art Unit 2881

September 18, 2007